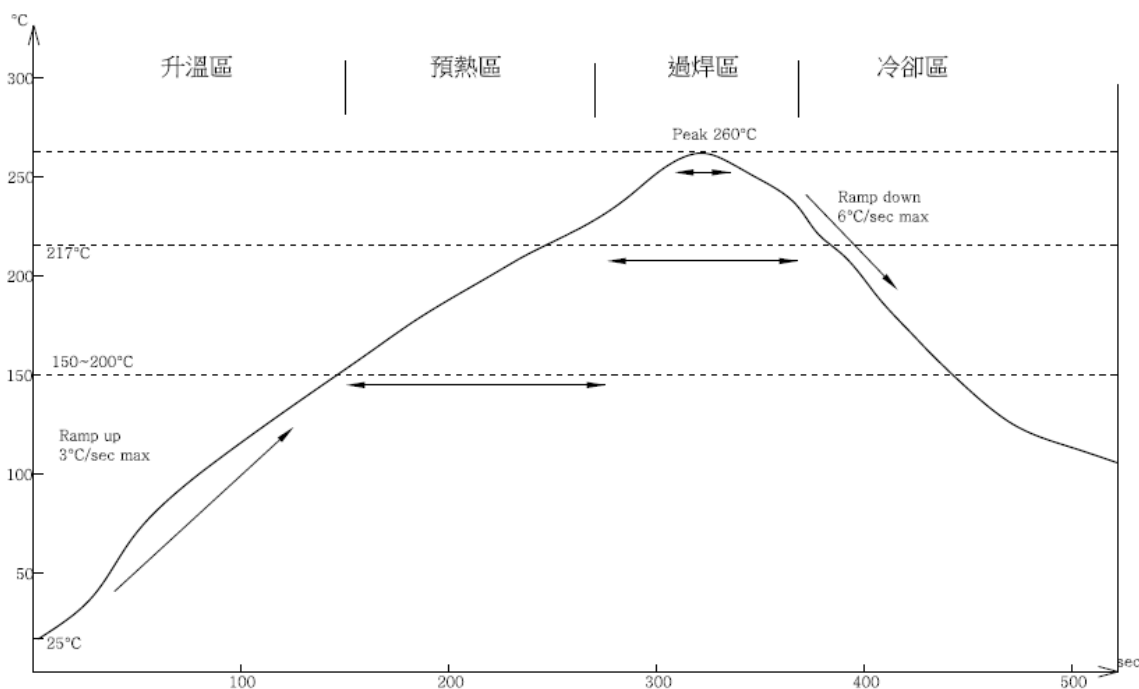


Reflow Soldering Profile

迴流焊接曲線圖

Parameter 參數	Reference 參考	Specification 規格
Ramp-up 升溫區	25°C ~150°C	3°C /S Max
Pre- heating 預熱區	150°C ~200°C	60~180sec
Reflow 迴焊區	217°C	60~150sec
Peak Temp(Tp)	260-/+5°C	20~40sec
Time 25°C to Tp	25°C ~ Peak Temp.	8 minutes maximum
Cooling 冷卻區	Peak Temp.~150°C	-6°C /S(Max)



This profile is the minimum requirement for evaluating soldering heat resistance of components. Heat transfer method used for reflow soldering is hot air convection. The actual air temperatures used to achieve the specified profile largely dependent on the reflow equipment.

這個曲線圖是評估元件器件焊接抗熱的基本要求。應用在對焊接中的熱傳遞方式是熱氣對流。達到特定曲線圖地實際溫度主要依賴與迴流焊接設備。

This profile is for reference only, Actual production requirement please refer to the specification.

此曲線圖僅供參考，實際生產條件要求請參考規格書。